



100% Material Declaration Data Sheet VO20

PK175 (v1.0) October 5, 2006

Material Declaration Data Sheet

Average Weight: 0.1 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00999	9.99%
	Silicon	7440-21-3	100.00		0.00999	
Die Attach Material					0.0026	2.60%
	Silver	7440-22-4	77.00		0.002002	
	Epoxy (EP)	Trade Secret	23.00		0.000598	
Mold Compound					0.04918	49.18%
	Epoxy Resin (EP)	Trade Secret	9.00		0.0044262	
	Phenolic Resin	Trade Secret	7.00		0.0034426	
	Carbon Black	1333-86-4	0.50		0.0002459	
	Silica	60676-86-0	82.50		0.0405735	
	Bismuth	7440-69-9	Max 1.00		0.0004918	
Leadframe					0.035	35.00%
	Copper	7440-50-8	97.50		0.034125	
	Iron	7439-89-6	2.35		0.0008225	
	Phosphorus	7723-14-0	0.03		0.0000105	
	Zinc	7440-66-6	0.12		0.000042	
Leadframe Plating					0.00008	0.08%
	Silver	7440-22-4	100.00		0.00008	
Bond Wire					0.00053	0.53%
	Gold	7440-57-5	99.9973		0.00052998569	
	Silver	7440-22-4	0.0005		0.0000000265	
	Calcium	7440-70-2	0.0022		0.0000001166	
Ext. Plating					0.00262	2.62%
	Tin	7440-31-5	85.00		0.002227	
	Lead	7439-92-1	15.00		0.000393	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.